The SN54F299 is obsolete and no longer supplied.

SN54F299, SN74F299 8-BIT UNIVERSAL SHIFT/STORAGE REGISTERS WITH 3-STATE OUTPUTS

SN54F299 ... J PACKAGE SN74F299 ... DW. N. OR NS PACKAGE

(TOP VIEW)

S0

OE2 3

G/Q_G []4

E/Q_E [5

C/Q_C []6

A/Q_A []7

CLR 9

4

5

6

Π7

8

10

SN54F299 ... FK PACKAGE (TOP VIEW)

> OE1 OE1 S0 VCC

3 2 1 20 19

9 10 11 12 13

SR CLK

CLR GND

 $\mathsf{Q}_{\mathsf{A}'}$

GND

G/Q_G

E/Q_E

C/Q_C

A/Q_A

 $\mathsf{Q}_{\mathsf{A}'}$

OE1 [2

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20 VCC

19 S1

18 SL

17 🛛 Q_H

16 H/Q_H

15 F/Q_F

14 D/QD

13 B/QB

12 CLK

11 SR

ŝ

17 🛛 Q_H′

16

15

14

′́18∏ SL

H/Q_H

F/Q_F

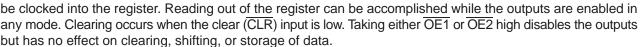
D/Q_D

- Four Modes of Operation:
 - Hold (Store)
 - Shift Right
 - Shift Left
 - Load Data
- Operates With Outputs Enabled or at High Impedance
- 3-State Outputs Drive Bus Lines Directly
- Can Be Cascaded for N-Bit Word Lengths
- Direct Overriding Clear
- Applications:
 - Stacked or Pushdown Registers
 - Buffer Storage
 - Accumulator Registers

description/ordering information

These 8-bit universal shift/storage registers feature multiplexed I/O ports to achieve full 8-bit data handling in a single 20-pin package. Two function-select (S0, S1) inputs and two output-enable ($\overline{OE1}$, $\overline{OE2}$) inputs can be used to choose the modes of operation listed in the function table.

Synchronous parallel loading is accomplished by taking both S0 and S1 high. This places the 3-state outputs in a high-impedance state and permits data that is applied on the I/O ports to



T _A	PACKAG	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 20	SN74F299N	SN74F299N
0°C to 70°C		Tube of 25	SN74F299DW	5000
0010700	SOIC – DW	Reel of 2000	SN74F299DWR	F299
	SOP – NS	Reel of 2000	SN74F299NSR	74F299

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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SN54F299, SN74F299 8-BIT UNIVERSAL SHIFT/STORAGE REGISTERS WITH 3-STATE OUTPUTS

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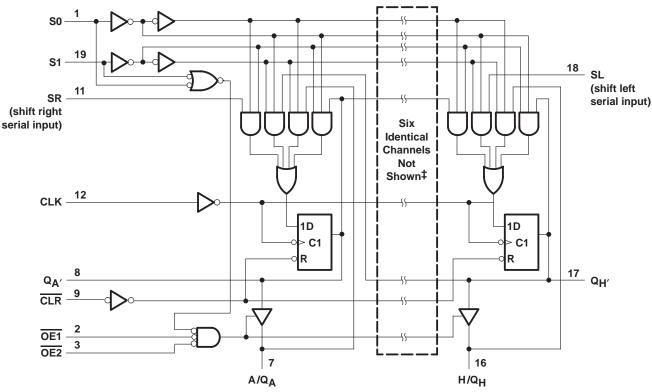
The SN54F299 is obsolete and no longer supplied.

								FU	INCTIO	N TABL	E							
MODE				INP	UTS				I/O PORTS								OUTPUTS	
MODE	CLR	S1	S0	OE1†	OE2†	CLK	SL	SR	A/Q _A	B/Q _B	C/QC	d/q _d	E/QE	F/Q _F	G/Q _G	H/Q _H	$Q_{A'}$	Q _{H′}
	L	Х	L	L	L	Х	Х	Х	L	L	L	L	L	L	L	L	L	L
Clear	L	L	Х	L	L	Х	Х	Х	L	L	L	L	L	L	L	L	L	L
	L	Н	Н	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	L	L
Hold	н	L	L	L	L	Х	Х	Х	Q _{A0}	Q _{B0}	Q _{C0}	Q_{D0}	Q_{E0}	Q _{F0}	Q _{G0}	Q _{H0}	Q _{A0}	Q _{H0}
TIOIU	Н	Х	Х	L	L	L	Х	Х	Q _{A0}	Q_{B0}	Q _{C0}	Q_{D0}	Q_{E0}	Q_{F0}	Q _{G0}	Q _{H0}	Q _{A0}	Q _{H0}
Shift	Н	L	Н	L	L	\uparrow	Х	Н	Н	Q _{An}	Q _{Bn}	QCn	Q _{Dn}	Q _{En}	Q _{Fn}	Q _{Gn}	Н	Q _{Gn}
Right	н	L	Н	L	L	↑	Х	L	L	Q _{An}	Q _{Bn}	QCn	Q _{Dn}	Q _{En}	Q _{Fn}	Q _{Gn}	L	QGn
Shift	Н	Н	L	L	L	\uparrow	Н	Х	Q _{Bn}	QCn	Q _{Dn}	Q _{En}	Q _{Fn}	Q _{Gn}	Q _{Hn}	Н	Q _{Bn}	Н
Left	Н	Н	L	L	L	↑	L	Х	Q _{Bn}	QCn	Q _{Dn}	Q _{En}	Q _{Fn}	Q _{Gn}	Q _{Hn}	L	Q _{Bn}	L
Load	Н	Н	Н	Х	Х	\uparrow	Х	Х	а	b	С	d	е	f	g	h	а	h

NOTE: a...h = the level of the steady-state input at inputs A through H, respectively. This data is loaded into the flip-flops while the flip-flop outputs are isolated from the I/O terminals.

[†] When one or both output-enable inputs are high, the eight I/O terminals are disabled to the high-impedance state; however, sequential operation or clearing of the register is not affected.

logic diagram (positive logic)



 \ddagger I/O ports not shown: B/Q_B (13), C/Q_C (6), D/Q_D (14), E/Q_E (5), F/Q_F (15), and G/Q_G (4).



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range, V _I (see Note 1)	
Input current range	
Voltage range applied to any output in the disabled or power-off state	. –0.5 V to 5.5 V
Voltage range applied to any output in the high state	-0.5 V to V _{CC}
Current into any output in the low state: Q _{A'} or Q _{H'}	40 mÅ
SN54F299 (Q _A thru Q _H)	40 mA
SN74F299 (Q _A thru Q _H)	48 mA
Package thermal impedance, θ_{JA} (see Note 2): DW package	58°C/W
N package	69°C/W
NS package	60°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input voltage ratings may be exceeded provided the input current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			S	SN54F299			N74F299	•	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage		2			2			V
V_{IL}	Low-level input voltage				0.8			0.8	V
Iк	Input clamp current				-18			-18	mA
	Libely local action for any of	$Q_{A'}$ or $Q_{H'}$			– 1			– 1	
ЮН	High-level output current	Q _A thru Q _H			- 3			- 3	mA
		$Q_{A'}$ or $Q_{H'}$			20			20	
IOL	Low-level output current QA thru QH				20			24	mA
TA	Operating free-air temperature		-55		125	0		70	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SN54F299, SN74F299 **8-BIT UNIVERSAL SHIFT/STORAGE REGISTERS** WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

_				S	N54F29	Э	S	N74F299	•	
P/	ARAMETER	TEST	CONDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT
VIK		V _{CC} = 4.5 V,	lj = – 18 mA			-1.2			-1.2	V
	$Q_{A'}$ or $Q_{H'}$		I _{OH} = – 1 mA	2.5	3.4		2.5	3.4		
		V _{CC} = 4.5 V	$I_{OH} = -1 \text{ mA}$	2.5	3.4		2.5	3.4		V
VOH	Q _A thru Q _H		$I_{OH} = -3 \text{ mA}$	2.4	3.3		2.4	3.3		V
	Any output	V _{CC} = 4.75 V,	$I_{OH} = -1 \text{ mA to } -3 \text{ mA}$				2.7			
	$Q_{A'}$ or $Q_{H'}$		I _{OL} = 20 mA		0.3	0.5		0.3	0.5	
VOL	L QA thru QH	$V_{CC} = 4.5 V$	I _{OL} = 20 mA		0.3	0.5				V
Q _A thru C			I _{OL} = 24 mA					0.35	0.5	
L.	A thru H		VI = 5.5 V			1			1	~ ^
II	Any other	V _{CC} = 5.5 V	V _I = 7 V			0.1			0.1	mA
t	A thru H		<u>)// 07)/</u>			70			70	
чн‡	Any other	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μA
	A thru H					-0.65			-0.65	
IIL‡	S0 or S1	V _{CC} = 5.5 V,	VI = 0.5 V			-1.2			-1.2	mA
Any other		7				-0.6			-0.6	
los§		V _{CC} = 5.5 V,	$V_{O} = 0$	-60		-150	-60		-150	mA
ICC		V _{CC} = 5.5 V,	See Note 4		68	95		68	95	mA

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] For I/O ports (Q_A thru Q_H), the parameters I_{IH} and I_{IL} include the off-state output current.

§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second. NOTE 4: I_{CC} is measured with OE1, OE2, and CLK at 4.5 V.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

				T _A = 2	V _{CC} = 5 V, T _A = 25°C ′F299		F299	SN74F299		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency				70		65		70	MHz
	Dula duratian	CLK high or low				8		7		
tw	Pulse duration	CLR low	7		8		7		ns	
	Setup time before	S0 or S1	High or low	8.5		9.5		8.5		
+	CLKT	A/Q _A thru H/Q _H , SR, or SL	High or low	5.5		6.5		5.5		ns
t _{su}	Inactive-state setup time before CLK ¹	CLR	High	7		13		7		115
		S0 or S1 High or I		0		0		0		
th	Hold time after CLK↑	A/Q _A thru H/Q _H , SR, or SL	High or low	2		2		2		ns

¶ Inactive-state setup time also is referred to as recovery time.



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The SN54F299 is obsolete and no longer supplied.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CI RI	V _{CC} = 5 V, C _L = 50 pF, R _L = 500 Ω, T _A = 25°C			= 50 pF = 500 9	, 2,	V,	UNIT
	((001101)		′ F299		SN54	F299			
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			70	100		65		70		MHz
^t PLH	OLK.	0	3.2	6.6	9	2.7	10.5	3.2	10	
^t PHL	CLK	$Q_{A'}$ or $Q_{H'}$	2.7	6.1	8.5	2.2	10	2.7	9.5	ns
^t PLH	CLK	O . thru O .	3.2	6.6	9	2.7	11	3.2	10	
^t PHL	CLK	Q _A thru Q _H	4.2	8.1	11	3.7	12.5	4.2	12	ns
		$Q_{A'}$ or $Q_{H'}$	3.7	7.1	9.5	3.2	11.5	3.7	10.5	
^t PHL	CLR	Q _A thru Q _H	5.7	10.6	14	5	15.5	5.7	15	ns
^t PZH	OE1 or OE2	0 4 0	2.7	5.6	8	2.2	10.5	2.7	9	
^t PZL	OE1 of OE2	Q _A thru Q _H	3.2	6.6	10	2.7	12	3.2	11	ns
^t PHZ	OE1 or OE2		1.7	4.1	6	1.7	9	1.7	7	20
^t PLZ	OET OF OE2	Q _A thru Q _H	1.2	3.6	5.5	1.2	7.5	1.2	6.5	ns

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



SN54F299, SN74F299 8-BIT UNIVERSAL SHIFT/STORAGE REGISTERS WITH 3-STATE OUTPUTS

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07V O Open **500** Ω TEST **S1** From Output Test From Output **Under Test** Point Under Test tPLH/tPHL Open C CL tPLZ/tPZL 7 V **500** Ω **500** Ω (see Note A) (see Note A) tPHZ/tPZH Open 7 V **Open Collector** LOAD CIRCUIT FOR LOAD CIRCUIT FOR **TOTEM-POLE OUTPUTS 3-STATE AND OPEN-DRAIN OUTPUTS** 3 V **Timing Input** 1.5 V 0 V tw th 3 V tsu 3 V 1.5 V 1.5 V Input 1.5 V **Data Input** 1.5 V 0 V 0 V VOLTAGE WAVEFORMS **VOLTAGE WAVEFORMS** PULSE DURATION 1.5 V SETUP AND HOLD TIMES 3 V 3 V Output 1.5 V 1.5 V 1.5 V 5 v Input Control 0 V 0 V tpzL -^tPLH - tPHL ^tPLZ Output ≈3.5 V VOH Waveform 1 In-Phase 1.5 V 1.5 V 1.5 V S1 at 7 V Output V_{OL} + 0.3 V VOL VOL (see Note B) ^tPHZ ^tPHL ⁻ K - ^tPLH tPZH -Output ۷он ۷он Waveform 2 **Out-of-Phase** V_{OH} – 0.3 V 1.5 V 1.5 V 1.5 V S1 at GND Output 0 V VOL (see Note B) **VOLTAGE WAVEFORMS VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES ENABLE AND DISABLE TIMES** INVERTING AND NONINVERTING OUTPUTS LOW- AND HIGH-LEVEL ENABLING

PARAMETER MEASUREMENT INFORMATION

NOTES: A. C₁ includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns, duty cycle = 50%.
- D. The outputs are measured one at a time, with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	n MSL Peak Temp ⁽³⁾
SN74F299DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F299DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F299DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F299DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F299DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F299N	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74F299N3	OBSOLETE	PDIP	Ν	20		TBD	Call TI	Call TI
SN74F299NE4	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74F299NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F299NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F299NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM

18-Sep-2008

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

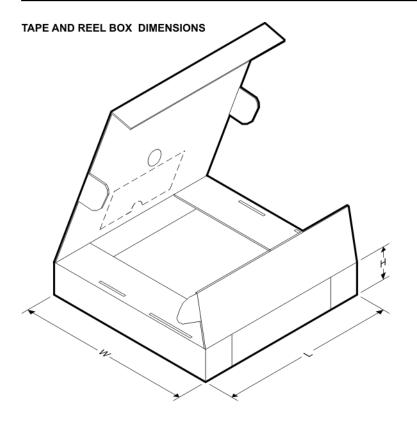


*All dimension	is are nominal												
De	vice		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74F2	299DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74F	299NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1



PACKAGE MATERIALS INFORMATION

5-Aug-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74F299DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74F299NSR	SO	NS	20	2000	346.0	346.0	41.0

MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AC.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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